

Issue	Cover Story			Trend & Analysis								Design & Technology						
				China Focus*	Design Trends	Opinions	Interview	Building Blocks	Analog	Engineers' Blog*	Peer-to-Peer*	Design Corner	Test and Measurement	China Fabless*	Teardown	Specials*	Trade Show Distribution	
July Booking deadline: May 21	Keeping A Lid On Power Consumption	Design: Voltage Regulators	Design: Digital Power	Silicon Valley Report	•	•	•	•	•	•	•	•	– Touch screens – Clock ICs – Audio design	Instrument calibration		•		
August Booking deadline: June 20	The Internet of Things: Impact On Lifestyle	Design: Near Field Communications	Design: RFID	Test and Measurement	•	•	•	•	•	•	•	•	– Multicore processors – Secure OS – AMOLED		Amplifier			
September Booking deadline: July 20	Are Automation Tools Ready For Next-Gen Design?	Design: Code Verification	Design: FPGA/PL-Based Design	Fresh Engineer: University Program	•	•	•	•	•	•	•	•	– Cloud computing – Solid-state drives – High-speed interface	Modular test		•	RF/Microwave	14 th International Optoelectronic Expo (Shenzhen - Sep 6-9)
October Booking deadline: August 20	Future of Wireless is LTE	Design: 5GHz/60GHz Communications	Design: Mobile Memory Tech	China Fabless Survey & Awards	•	•	•	•	•	•	•	•	– MEMS sensors – ADCs/DACs – DSPs	EMC	PMIC			– Taitronics - Taipei International Electronics Show (Taipei - Oct 9-12) – 80 th China Electronics Fair (Shanghai - Oct 30 - Nov 1)
November Booking deadline: September 18	Renewable Energy: Challenges & Opportunities	Design: Smart grid	Design: LED lighting	Smart Phone Design	•	•	•	•	•	•	•	•	– MOSFETs/IGBTs – 3D displays – Video surveillance	Hardware/software coverfication		•	Embedded Special	– 80 th China Electronics Fair (Shanghai - Oct 30 - Nov 1) – China Hi-tech Fair (Shenzhen - Nov 16-21)
December Booking deadline: October 19	The Road To Competitive Electric/Hybrid Vehicles	Design: Driver Assistance	Design: Microcontrollers	Automotive Electronics	•	•	•	•	•	•	•	•	– HD camera design – Medical electronics – Wireless power	LTE test	Wireless		Analog Special	

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Remark: * for China edition only.

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Note

The publisher retains the right to reschedule any topic in the calendar.